

CLEAR LOGIC

CL7160E  
CL7160S

Laser Processed Logic Device Family

### Key Features

- ◆ Laser Processed Logic Device (LPLD™) technology offers the ultimate combination of performance, flexibility, and low cost
- ◆ Functionally, architecturally, and electrically compatible with industry-standard Altera® MAX® 7000
- ◆ High Density
  - 3,200 Usable gates
  - 160 Macrocells
  - 136 Maximum user I/O pins
- ◆ Laser fuse technology provides very fast, dense interconnect routing
- ◆ Low current consumption
- ◆ Supports 3.3 volt or 5.0 volt I/O operation
- ◆ Alpha particle immune

### CL7000 Product Family Overview

Parameter	CL7128E	CL7160E	CL7192E	CL7256E
	CL7128S	CL7160S	CL7192S	CL7256S
Useable Gates	2,500	3,200	3,750	5,000
Macrocells	128	160	192	256
Logic Blocks	8	10	12	16
Max user I/O pins	100	104	124	164
Speed Grades	-5, -6, -7, -10, -12, -15, -20	-5, -6, -7, -10, -12, -15, -20	-6, -7, -10, -12, -15, -20	-6, -7, -10, -12, -15, -20
Packages	84-pin PLCC 100-pin TQFP 100-pin PQFP 160-pin PQFP	84-pin PLCC 100-pin TQFP 100-pin PQFP 160-pin PQFP	160-pin PQFP	160-pin PQFP 208-pin PQFP 208-pin RQFP

7K tbl 01B

**Description**

The Clear Logic CL7000 Laser Processed Logic Device (LPLD<sup>®</sup>) family offers the ultimate combination of performance, flexibility, and cost. This family is a system level second source to Altera MAX<sup>®</sup> 7000, 7000E, and 7000S products. For designs not requiring in-system reprogrammability, design verification can be performed using the programmable Altera devices, and Clear Logic LPLDs can be used for low cost, high volume production.

Clear Logic's innovative laser-based technology eliminates NRE costs, test vector development, ordering minimums and long lead times. No re-simulation or re-layout is required, as the device uses a cell-based, PLD-like architecture. Clear Logic's NoFault<sup>®</sup> technology ensures complete test coverage through the use of specialized testing modes which are transparent to the user.

The Clear Logic CL7000 Laser Processed Logic Device family is based upon a large array of macrocells. Each macrocell contains a logic array with five product terms, a product-term select matrix, and a configurable register. A group of sixteen macrocells forms a block. Laser-configured metal fuses implement logical functions and control signal routing.

Laser configuration provides reduced cost and enhanced performance. These inherent performance benefits include extremely consistent propagation delays, reduced power consumption, and improved immunity to noise and upset events.

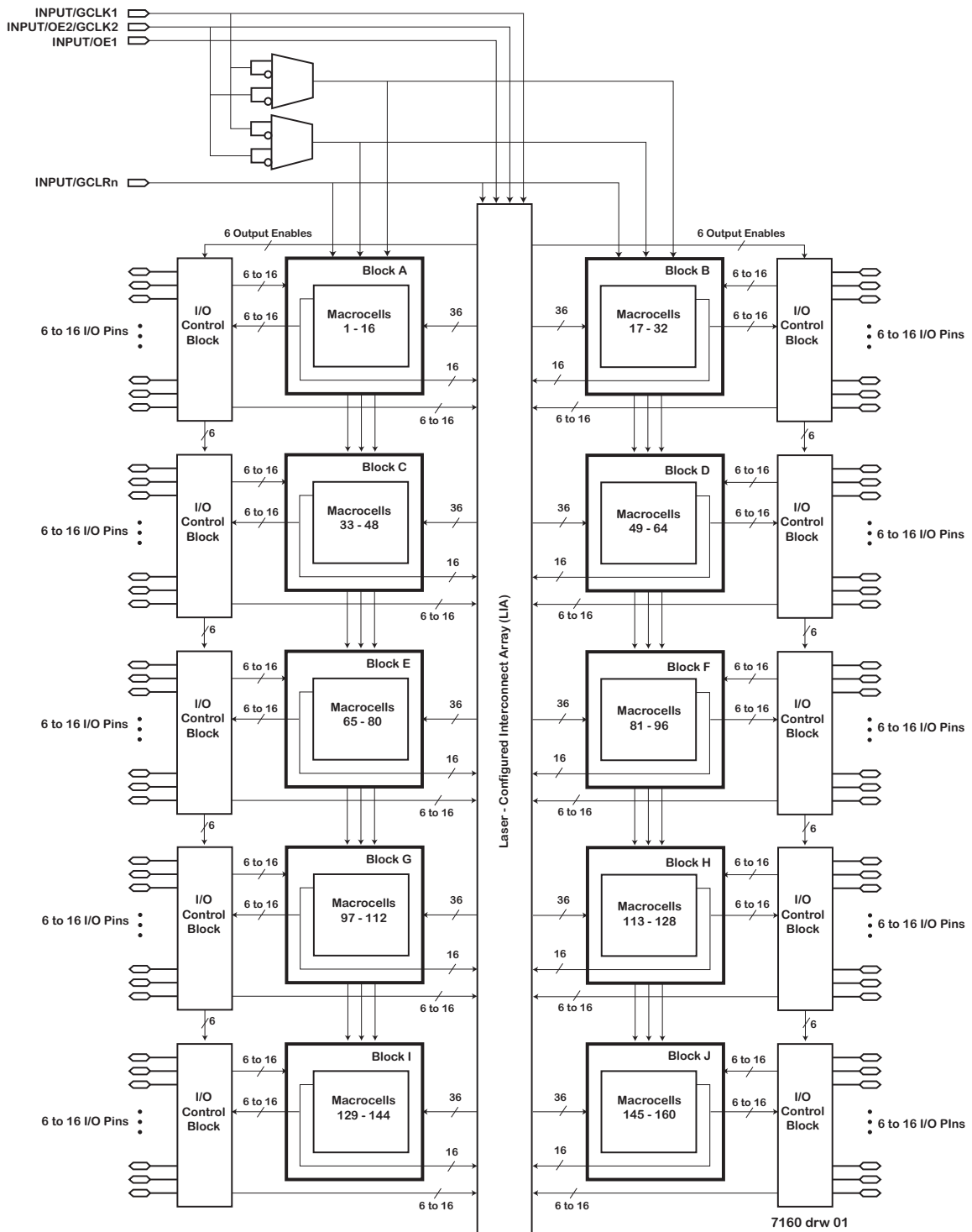
**Additional Information**

For further information on designing with the CL7000 LPLD family, please consult the following documents:

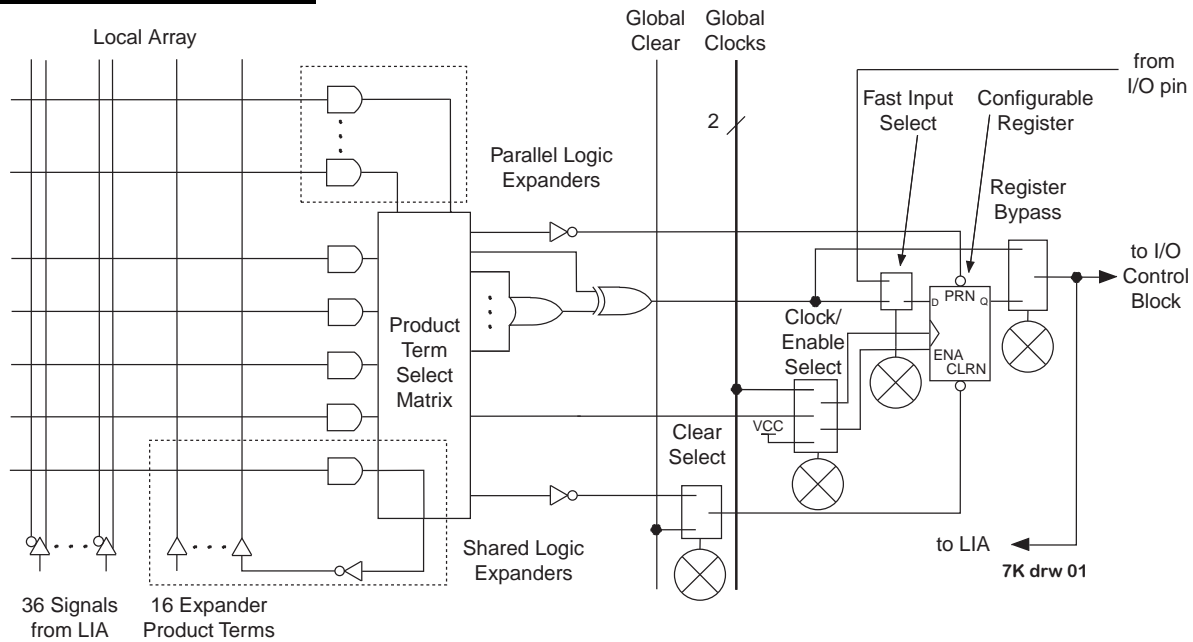
- ◆ AN-01: Requesting a First Article. This document provides instructions on how to submit a bitstream file for generation of first articles.
- ◆ AN-02: Clear Logic Packaging Guide. This document provides specifications and drawings for packages used by the CL7000 family.
- ◆ AN-09: CL7000 Technology White Paper. This document outlines the technologies employed by the CL7000 LPLD family.
- ◆ AN-10: Calculating CL7000 Power Consumption. This document provides guidelines for calculating power consumption based on design characteristics.
- ◆ AN-11: CL7000 Test Methodology. This document describes how Clear Logic provides 100% stuck-at fault coverage.

- ◆ AN-12: CL7000 LPLD Timing and Function Compatibility. This document shows how a seamless conversion from CPLD to ASIC can be achieved with no additional engineering with Clear Logic.

**Block Diagram**



**Macrocell Diagram**



**Pin Configuration**

Pin Name	84 pin PLCC	100 pin TQFP	100 pin PQFP	160 pin PQFP
INPUT/GCLK1	83	87	89	139
INPUT/GCLRn	1	89	91	141
INPUT/OE1	84	88	90	140
INPUT/OE2/GCLK2	2	90	92	142
TDI	14	4	6	9
TMS	23	15	17	22
TCK	62	62	64	99
TDO	71	73	75	112
GND	7, 19, 32, 42, 47, 59, 72, 82	38, 86, 11, 26, 43, 59, 74, 95	13, 28, 40, 45, 61, 76, 88, 97	17, 42, 60, 66, 95, 113, 138, 148
VCCINT	3, 43	39, 91	41, 93	61, 143
VCCIO	13, 26, 38, 53, 66, 78	3, 18, 34, 51, 66, 82	5, 20, 36, 53, 68, 84	8, 26, 55, 79, 104, 133
NC (No Connect)	6, 39, 46, 79	-	-	1, 2, 3, 4, 5, 6, 34, 35, 36, 37, 38, 39, 40, 45, 46, 47, 74, 75, 76, 81, 82, 83, 84, 85, 86, 87, 115, 116, 117, 118, 119, 120, 124, 125, 126, 127, 154, 155, 156, 157
<b>Total user I/O pins</b>	<b>60</b>	<b>80</b>	<b>80</b>	<b>100</b>

7160 tbl 01

**DC Electrical Specifications**

**Recommended Operating Conditions**

Symbol	Parameter	Conditions	Min	Max	Unit	
V <sub>CCINT</sub>	Supply voltage, internal logic and input buffers		Commercial Grade Devices	4.75	5.25	V
			Industrial Grade Devices	4.50	5.50	V
V <sub>CCIO</sub>	DC input voltage		5.0 volt commercial	4.75	5.25	V
			5.0 volt industrial	4.50	5.50	V
			3.3 volt operation	3.00	3.60	V
V <sub>I</sub>	Input voltage		-0.5	V <sub>CCINT</sub> +0.5	V	
V <sub>O</sub>	Output voltage		0	V <sub>CCIO</sub>	V	
T <sub>A</sub>	Operating temperature		Commercial temperature range	0	70	°C
			Industrial temperature range	-40	85	°C
T <sub>J</sub>	Junction Operating temperature		Commercial temperature range	0	90	°C
			Industrial temperature range	-40	105	°C
t <sub>R</sub>	Input signal rise time			40	ns	
t <sub>F</sub>	Input signal fall time			40	ns	
t <sub>RVCC</sub>	V <sub>CC</sub> rise time			100	ms	

7K tbl 02

**Absolute Maximum Ratings**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply voltage	With respect to ground	-2.0	7.0	V
V <sub>I</sub>	DC input voltage <sup>[1]</sup>	With respect to ground	-2.0	7.0	V
I <sub>OUT</sub>	DC output current, per pin		-25	25	mA
T <sub>STG</sub>	Storage temperature	No bias	-65	150	°C
T <sub>AMB</sub>	Ambient temperature	Under bias	-65	135	°C
T <sub>J</sub>	Junction temperature	Under bias		135	°C

7K tbl 03

## DC Electrical Specifications cont.

### DC Electrical Characteristics (over the operating range)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{IH}$	High-level input Voltage		2.0	$V_{CCINT} + 0.5$	V
$V_{IL}$	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	V
$V_{OH}$	5.0-V high-level TTL output Voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V}$	2.4		V
	3.3-V high-level TTL output Voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V}$	2.4		V
	3.3-V high-level CMOS output Voltage	$I_{OH} = -0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V}$	$V_{CCIO} - 0.2$		V
$V_{OL}$	5.0-V high-level TTL output Voltage	$I_{OL} = 12 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V}$		0.45	V
	3.3-V high-level TTL output Voltage	$I_{OL} = 12 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V}$		0.45	V
	3.3-V high-level CMOS output Voltage	$I_{OL} = 0.1 \text{ mA DC}, V_{CCIO} = 3.0 \text{ V}$		0.2	V
$I_{IN}$	Input Leakage Current	$V_I = V_{CC}$ or GND	-10	10	$\mu\text{A}$
$I_{OZ}$	Output Leakage Current	$V_O = V_{CC}$ or GND	-40	40	$\mu\text{A}$

7K tbl 04

### Capacitance

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input Capacitance	$V_{IN} = 0 \text{ V}, f = 1.0 \text{ MHz}$		10	pF
$C_{OUT}$	Output Capacitance	$V_{OUT} = 0 \text{ V}, f = 1.0 \text{ MHz}$		10	pF

7K tbl 05

**AC Electrical Specifications**

**I/O Element Timing Parameters <sup>[4]</sup>**

Symbol	Parameter	Conditions	Speed: -5		Speed: -6		Speed: -7		Unit
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C <sub>L</sub> = 35 pF		5.0		6.0		7.5	ns
t <sub>PD2</sub>	I/O input to non-registered output	C <sub>L</sub> = 35 pF		5.0		6.0		7.5	ns
t <sub>SU</sub>	Global clock setup time		2.9		3.4		4.2		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C <sub>L</sub> = 35 pF		3.2		3.9		4.8	ns
t <sub>CH</sub>	Global clock high time		2.0		3.0		3.0		ns
t <sub>CL</sub>	Global clock low time		2.0		3.0		3.0		ns
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		ns
t <sub>AH</sub>	Array clock hold time		1.8		1.7		2.1		ns
t <sub>ACO1</sub>	Array clock to output delay	C <sub>L</sub> = 35 pF		5.4		6.4		7.9	ns
t <sub>ACH</sub>	Array clock high time		2.5		3.0		3.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		3.0		3.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C <sub>L</sub> = 35 pF	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		6.7		8.2	ns
f <sub>CNT</sub>	Max. internal global clock frequency		175.4		149.3		122.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.5		6.7		8.2	ns
f <sub>ACNT</sub>	Max. internal array clock frequency		175.4		149.3		122.0		MHz

7K tbl 06C1

## AC Electrical Specifications cont.

## External Timing Parameters

Symbol	Parameter	Conditions	Speed: -10P		Speed: -10		Speed: -12		Unit
			Min	Max	Min	Max	Min	Max	
$t_{PD1}$	Input to non-registered output	$C_L = 35 \text{ pF}$		10.0		10.0		12.0	ns
$t_{PD2}$	I/O input to non-registered output	$C_L = 35 \text{ pF}$		10.0		10.0		12.0	ns
$t_{SU}$	Global clock setup time		7.0		7.0		10.0		ns
$t_H$	Global clock hold time		0.0		0.0		0.0		ns
$t_{FSU}$	Global clock setup time of fast input		3.0		3.0		3.0		ns
$t_{FH}$	Global clock hold time of fast input		0.5		0.5		0.0		ns
$t_{CO1}$	Global clock to output delay	$C_L = 35 \text{ pF}$		5.0		5.0		6.0	ns
$t_{CH}$	Global clock high time		4.0		4.0		4.0		ns
$t_{CL}$	Global clock low time		4.0		4.0		4.0		ns
$t_{ASU}$	Array clock setup time		2.0		2.0		4.0		ns
$t_{AH}$	Array clock hold time		3.0		3.0		4.0		ns
$t_{ACO1}$	Array clock to output delay	$C_L = 35 \text{ pF}$		10.0		10.0		12.0	ns
$t_{ACH}$	Array clock high time		4.0		4.0		5.0		ns
$t_{ACL}$	Array clock low time		4.0		4.0		5.0		ns
$t_{ODH}$	Output data hold time after clock	$C_L = 35 \text{ pF}$	1.0		1.0		1.0		ns
$t_{CNT}$	Minimum global clock period			10.0		10.0		11.0	ns
$f_{CNT}$	Max. internal global clock frequency		100.0		100.0		90.9		MHz
$t_{ACNT}$	Minimum array clock period			10.0		10.0		11.0	ns
$f_{ACNT}$	Max. internal array clock frequency		100.0		100.0		90.9		MHz

7K tbl 06C2



**AC Electrical Specifications cont.**

**External Timing Parameters**

Speed: -15

Speed: -20

Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t <sub>PD1</sub>	Input to non-registered output	C <sub>L</sub> = 35 pF		15.0		20.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C <sub>L</sub> = 35 pF		15.0		20.0	ns
t <sub>SU</sub>	Global clock setup time		11.0		12.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		3.0		5.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C <sub>L</sub> = 35 pF		8.0		12.0	ns
t <sub>CH</sub>	Global clock high time		5.0		6.0		ns
t <sub>CL</sub>	Global clock low time		5.0		6.0		ns
t <sub>ASU</sub>	Array clock setup time		4.0		5.0		ns
t <sub>AH</sub>	Array clock hold time		4.0		5.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C <sub>L</sub> = 35 pF		15.0		20.0	ns
t <sub>ACH</sub>	Array clock high time		6.0		8.0		ns
t <sub>ACL</sub>	Array clock low time		6.0		8.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C <sub>L</sub> = 35 pF	1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			13.0		16.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13.0		16.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency		76.9		62.5		MHz

7K tbl 06C3

## AC Electrical Specifications cont.

Internal Timing Parameters<sup>[4]</sup>

Symbol	Parameter	Conditions	Speed: -5		Speed: -6		Speed: -7		Unit
			Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.2		0.3	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.2		0.3	ns
t <sub>FIN</sub>	Fast input delay			2.2		2.6		3.2	ns
t <sub>SEXP</sub>	Shared expander delay			3.1		3.6		4.3	ns
t <sub>PEXP</sub>	Parallel expander delay			0.9		1.0		1.3	ns
t <sub>LAD</sub>	Logic array delay			2.6		2.8		3.4	ns
t <sub>LAC</sub>	Logic control array delay			2.5		2.8		3.4	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.7		0.9	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		0.2		0.4		0.5	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		0.7		0.9		1.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		5.2		5.4		5.5	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		4.0		4.0		4.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		4.5		4.5		4.5	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		9.0		9.0		9.0	ns
t <sub>ZZ</sub>	Output buffer disable delay	C <sub>L</sub> = 5 pF <sup>[3]</sup>		4.0		4.0		4.0	ns
t <sub>SU</sub>	Register setup time		0.8		1.0		1.2		ns
t <sub>H</sub>	Register hold time		1.7		1.6		2.0		ns
t <sub>FSU</sub>	Register setup time of fast input		1.9		1.9		2.2		ns
t <sub>FH</sub>	Register hold time of fast input		0.6		0.6		0.8		ns
t <sub>RD</sub>	Register delay			1.2		1.3		1.6	ns
t <sub>COMB</sub>	Combinatorial delay			0.9		1.0		1.3	ns
t <sub>IC</sub>	Array clock delay			2.7		2.9		3.5	ns
t <sub>EN</sub>	Register enable time			2.6		2.8		3.4	ns
t <sub>GLOB</sub>	Global control delay			1.6		2.0		2.4	ns
t <sub>PRE</sub>	Register preset time			2.0		2.4		3.0	ns
t <sub>CLR</sub>	Register clear time			2.0		2.4		3.0	ns
t <sub>LIA</sub>	LIA delay			1.1		1.6		2.0	ns

7K tbl 07C1

**AC Electrical Specifications cont.**

**Internal Timing Parameters<sup>[4]</sup>**

Speed: -10P

Speed: -10

Speed: -12

Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
t <sub>IN</sub>	Input pad and buffer delay			0.5		0.5		2.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.5		0.5		2.0	ns
t <sub>FIN</sub>	Fast input delay			1.0		1.0		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			5.0		5.0		7.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.8		0.8		1.0	ns
t <sub>LAD</sub>	Logic array delay			5.0		5.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			5.0		5.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay			2.0		2.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		1.5		1.5		3.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		2.0		2.0		4.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		5.5		5.5		7.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		5.0		5.0		6.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		5.5		5.5		7.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		9.0		9.0		10.0	ns
t <sub>XZ</sub>	Output buffer disable delay	C <sub>L</sub> = 5 pF <sup>[3]</sup>		5.0		5.0		6.0	ns
t <sub>SU</sub>	Register setup time		2.0		2.0		4.0		ns
t <sub>H</sub>	Register hold time		3.0		3.0		4.0		ns
t <sub>FSU</sub>	Register setup time of fast input		3.0		3.0		2.0		ns
t <sub>FH</sub>	Register hold time of fast input		0.5		0.5		2.0		ns
t <sub>RD</sub>	Register delay			2.0		2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			2.0		2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			5.0		5.0		5.0	ns
t <sub>EN</sub>	Register enable time			5.0		5.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0		0.0	ns
t <sub>PRE</sub>	Register preset time			3.0		3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			3.0		3.0		3.0	ns
t <sub>LIA</sub>	LIA delay			1.0		1.0		1.0	ns

7K tbl 07C2

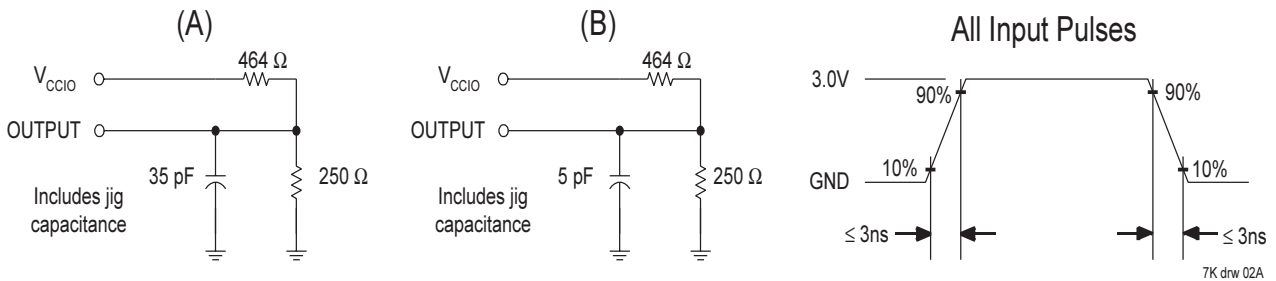
## AC Electrical Specifications cont.

Internal Timing Parameters<sup>[4]</sup>

Symbol	Parameter	Conditions	Speed: -15		Speed: -20		Unit
			Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			2.0		3.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			2.0		3.0	ns
t <sub>FIN</sub>	Fast input delay			2.0		4.0	ns
t <sub>SEXP</sub>	Shared expander delay			8.0		9.0	ns
t <sub>PEXP</sub>	Parallel expander delay			1.0		2.0	ns
t <sub>LAD</sub>	Logic array delay			6.0		8.0	ns
t <sub>LAC</sub>	Logic control array delay			6.0		8.0	ns
t <sub>IOE</sub>	Internal output enable delay			3.0		4.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		4.0		5.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		5.0		6.0	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		8.0		9.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 5.0 V	C <sub>L</sub> = 35 pF		6.0		10.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off, V <sub>CCIO</sub> = 3.3 V	C <sub>L</sub> = 35 pF		7.0		11.0	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on, V <sub>CCIO</sub> = 5.0 V or 3.3 V	C <sub>L</sub> = 35 pF		10.0		14.0	ns
t <sub>XZ</sub>	Output buffer disable delay	C <sub>L</sub> = 5 pF <sup>[3]</sup>		6.0		10.0	ns
t <sub>SU</sub>	Register setup time		4.0		4.0		ns
t <sub>H</sub>	Register hold time		4.0		5.0		ns
t <sub>FSU</sub>	Register setup time of fast input		2.0		4.0		ns
t <sub>FH</sub>	Register hold time of fast input		1.0		3.0		ns
t <sub>RD</sub>	Register delay			1.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			1.0		1.0	ns
t <sub>IC</sub>	Array clock delay			6.0		8.0	ns
t <sub>EN</sub>	Register enable time			6.0		8.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		3.0	ns
t <sub>PRE</sub>	Register preset time			4.0		4.0	ns
t <sub>CLR</sub>	Register clear time			4.0		4.0	ns
t <sub>LIA</sub>	LIA delay			2.0		3.0	ns

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## AC Test Conditions



## Notes to Tables

1. During transitions, inputs may undershoot to -2.0V for periods shorter than 20ns. Otherwise, minimum DC input voltage is 0.3V.
2. Typical values are at V<sub>CC</sub> of 5.0 volts and ambient temperature of 25 °C.
3. Guaranteed but not tested. Characterized initially, and after any design changes which may affect these parameters.
4. Internal timing delays are based on characterization, and cannot be explicitly tested. Internal timing parameters should be used for performance estimation only.

## Revision History

- |               |  |
|---------------|--|
| 11 Jan. 1999: | Created new document   |
| 30 Apr. 1999: | Recompiled databook, no changes.   |
| 31 July 1999: | Added -6ns speed grade, revised the Product Family Overview, corrected Pin Configuration Table |
| 13 Oct. 1999: | Corrected typographical error in AC Test Condition diagram (W changed to Ω)                    |
| 1 Dec. 2000:  | Updated application note reference.  |

**Ordering Information**

Part Number	Temperature Range	Package Type	Speed	Altera Equivalent
CL7160ELC84-20	Commercial	84-pin Plastic LCC	-20	EPM7160ELC84-20
CL7160ELC84-15			-15	EPM7160ELC84-15
CL7160ELC84-12			-12	EPM7160ELC84-12
CL7160ELC84-10			-10	EPM7160ELC84-10
CL7160ELC84-6			-6	N/A
CL7160ELI84-20			Industrial	
CL7160EQC100-20	Commercial	100-pin Plastic QFP	-20	EPM7160EQC100-20
CL7160EQC100-15			-15	EPM7160EQC100-15
CL7160EQC100-12			-12	EPM7160EQC100-12
CL7160EQC100-10			-10	EPM7160EQC100-10
CL7160EQC100-10P			-10 PCI	EPM7160EQC100-10P
CL7160EQC100-6			-6	N/A
CL7160EQI100-15	Industrial		-15	EPM7160EQC100-15
CL7160EQC160-20	Commercial	160-pin Plastic QFP	-20	EPM7160EQC160-20
CL7160EQC160-15			-15	EPM7160EQC160-15
CL7160EQC160-12			-12	EPM7160EQC160-12
CL7160EQC160-10			-10	EPM7160EQC160-10
CL7160EQC160-10P			-10 PCI	EPM7160EQC160-10P
CL7160EQC84-6			-6	N/A
CL7160EQI160-15	Industrial		-15	EPM7160EQI160-15
CL7160SLC84-10	Commercial	84-pin Plastic LCC	-10	EPM7160SLC84-10
CL7160SLC84-7			-7	EPM7160SLC84-7
CL7160SLC84-6			-6	N/A
CL7160STC100-10		100-pin Thin QFP	-10	EPM7160STC100-10
CL7160STC100-7			-7	EPM7160STC100-7
CL7160STC100-6			-6	N/A
CL7160SQC160-10		160-pin Plastic QFP	-10	EPM7160SQC160-10
CL7160SQC160-7			-7	EPM7160SQC160-7
CL7160EQC84-6			-6	N/A

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